

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	38877	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:05
L2	37291	257/E23.002,E23.01- E23.079,E23.112, E23.132-E23.133, E23.119,E23.121, E23.167,E23.144.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:13
L3	526	257/E23.112.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:13
L4	2115	257/E23.167.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:13
L5	1653	257/E23.144.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:14
L6	2673	257/713	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:14
L7	1416	257/713.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:14
L8	814	257/759.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:14
L9	95	257/716.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:14
L10	855	257/717.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:15
L11	6	US-3846825-\$.DID. OR US-5412247-\$.DID. OR US-6054752-\$.DID. OR US-20030003699-\$.DID. OR US-20030107041-\$. DID. OR US- 20050032347-\$.DID.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:18
L12	3	"2003030247"	DERWENT	OR	ON	2009/07/05 17:23
L13	4	"1403786"	DERWENT	OR	ON	2009/07/05 17:24

L14	552	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and insulating and ((dielectric breakdown) near3 strength)	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:26
L15	183	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and insulating and ((dielectric breakdown) near3 strength) and (surface near contour or filler or reinforc\$5)	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:27
L16	288	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and insulating and ((dielectric breakdown) near3 strength) and (surface near contour or filler or reinforc\$5or dimensional stability)	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:36
L17	139	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and insulating and ((dielectric breakdown) near3 strength) and (surface near contour or filler or reinforc\$5or dimensional near stability)	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:36

L18	196	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.cds. and insulating and ((dielectric breakdown) near3 strength) and (surface near contour or filler or reinforc\$5 or dimensional near stability)	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:36
L19	4010	Mv\$1cm	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 17:51
L20	18	(polyimide or epoxy) near3 insulat\$4 near3 film and mv\$1cm	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/05 17:51
L21	120	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.cds. and insulating and ((dielectric breakdown) near3 strength) and (surface near contour or filler or reinforc\$5 or dimensional near stability) and resin	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 18:28
L22	139	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.cds. and (insulating dielectric) near film same filler	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 18:42
L23	41	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.cds. and (insulating dielectric) near film same filler and vacuum	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 18:44

L24	20	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and (insulating dielectric) near film same3 filler and vacuum near3 laminat\$4	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 18:49
L25	85	257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls. and (insulating dielectric) near layer same3 filler and vacuum near3 laminat\$4	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 18:51
L26	154	(insulating dielectric) near layer same3 filler and vacuum near3 laminat\$4 and semiconductor	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 19:05
L27	105	(insulating dielectric) near layer same3 filler and vacuum near3 laminat\$4 and semiconductor not 257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 19:05
L28	105	(insulating dielectric) near layer same3 filler and vacuum near3 laminat\$4 and semiconductor not 257/713,759,716, E23.002,E23.01-E23.079, E23.112,E23.132- E23.133,E23.119, E23.121,E23.167, E23.144.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/05 19:07
L29	2	"5414297".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/05 19:32

L30	4	"2000037481".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/05 19:36
L31	5	"037481".ap.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/05 19:36
L32	0	(US-3846825-\$.DID. OR US-5412247-\$.DID. OR US-6054752-\$.DID. OR US-20030003699-\$.DID. OR US-20030107041-\$. DID. OR US- 20050032347-\$.DID.) and filler	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 19:57
L33	6	(US-3846825-\$.DID. OR US-5412247-\$.DID. OR US-6054752-\$.DID. OR US-20030003699-\$.DID. OR US-20030107041-\$. DID. OR US- 20050032347-\$.DID.) and aluminum	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 19:58
L34	1	"5510174".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/07/05 20:00
S1	248	dielectric near3 strength same (insulat\$4) and (insulat\$4) same kV \$1mm	US-PGPUB; USPAT	OR	OFF	2009/04/10 10:38
S2	70	S1 and semiconductor	US-PGPUB; USPAT	OR	OFF	2009/04/10 10:38
S3	248	(dielectric near3 strength or (maximum near2 electrical adj field) near5 strength) same (insulat \$4) and (insulat\$4) same kV\$1mm	US-PGPUB; USPAT	OR	OFF	2009/04/10 10:42
S4	0	"WO 03/030247"	DERWENT	OR	OFF	2009/04/10 10:57
S5	1	"WO 03030247"	DERWENT	OR	OFF	2009/04/10 10:57
S6	11	(polyimide or epoxy) near3 insulat\$4 and kv \$1mm	DERWENT	OR	OFF	2009/04/10 11:39

S7	141	(polyimide or epoxy) near3 insulat\$4 and kv \$1mm	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/10 11:40
S8	23	(polyimide or epoxy) near3 insulat\$4 near3 film and kv\$1mm	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/10 11:40
S9	2	"20020001763"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/10 11:45
S23	3	"20050032347"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/04/29 09:52
S24	2	(insulat\$3 near film) same (mesh with filler)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:28
S25	3	(insulat\$3 near3 film) same (mesh with filler)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:28
S26	15	(insulat\$3 near3 layer) same (mesh with filler)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:29
S27	460	(insulat\$3 near3 layer) same thermal with filler	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:30
S28	96	(insulat\$3 near3 layer) same thermal with filler and filler same (mesh fabric)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:30
S29	70	(insulat\$3 near3 layer) same thermal with filler and filler same (mesh fabric) and semiconductor	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:30
S30	8	(insulat\$3 near3 layer) same thermal with filler and filler same (mesh fabric) and (power near semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:32
S31	8	(insulat\$3 near3 layer) same thermal with filler and filler same (mesh fabric woven net) and (power near semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:37

S32	8	(insulat\$3 near3 layer) same thermal with filler and filler same (mesh fabric woven net network) and (power near semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:37
S33	78	(insulat\$3 near3 layer) same (thermal with filler) and (filler same (mesh fabric woven net network interwoven)) and (semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 17:40
S34	52	(insulat\$3 near3 layer) same (thermal with filler) and (filler same (PTFE)) and (semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:32
S35	5	(dielectric near3 layer) same (thermal with filler) and (filler same (PTFE)) and (semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:40
S36	22	(dielectric near3 layer) same (thermal with filler) and (filler same (reinforc \$5)) and (semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:45
S37	283	(dielectric near3 layer) and (filler same (reinforc \$5)) and (semiconductor)	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:45
S38	150706	(dielectric near3 layer) and (filler same (reinforc \$5)) and (semiconductor) and heat sink	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:46
S39	40	(dielectric near3 layer) and (filler same (reinforc \$5)) and (semiconductor) and heat near sink	US-PGPUB; USPAT	OR	OFF	2009/07/02 18:46

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